



Statement of Compliance

Requested Part

30 September 2015

1393217-8

(Part 1 of 1)


RE030024

Part Status: Active

Mil-Spec Certified: No

EU RoHS/ELV Code: Converted to EU RoHS but not ELV Compliant

Solder Process Capability Code: Wave solder capable to 260°C

China RoHS:  Restricted Materials Above Threshold

Exemptions: 8(b) - Cd-Electrical Contacts

REACH Oct 2008 SvHC Compliance: Contains no REACH October 2008 SvHC(s)

REACH Jan/Mar 2010 SvHC Compliance: Contains no REACH Jan/Mar 2010 SvHC(s)

REACH June 2010 SvHC Compliance: Contains no REACH June 2010 SvHC(s)

REACH December 2010 SvHC Compliance: Contains no REACH December 2010 SvHC(s)

REACH June 2011 SvHC Compliance: Contains no REACH June 2011 SvHC(s)

REACH December 2011 SvHC Compliance: Contains no REACH December 2011 SvHC(s)

REACH June 2012 SvHC Compliance: Contains no REACH June 2012 SvHC(s)

REACH December 2012 SvHC Compliance: Contains no REACH December 2012 SvHC(s)

REACH June 2013 SvHC Compliance: Contains no REACH June 2013 SvHC(s)

REACH December 2013 SvHC Compliance: Contains no REACH December 2013 SvHC(s)

REACH June 2014 SvHC Compliance: Contains no REACH June 2014 SvHC(s)

REACH December 2014 SvHC Compliance: Contains no REACH December 2014 SvHC(s)

REACH June 2015 SvHC Compliance: Contains no REACH June 2015 SvHC(s)

The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hex chrome, mercury, PBB, PBDE, and 0.01% for cadmium, or qualify for an exemption to above limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Note that any exemptions taken in this case would not include application specific exemptions (e.g. lead in solder for servers) as TE cannot determine where component products will be used.

Additionally, the part numbers that are as 5 of 6 compliant meet the material limits described above, except that these products have lead in the solderable interface only. These products may be suitable for use in an application that has an exemption for the use of lead in solder (e.g. servers, network infrastructure, etc).

Finished electrical and electronic products will be CE marked as required by Directive 2011/65/EU (RoHS2). Components may not be CE marked.

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information provided by our suppliers. This information is subject to change.



Halogen Content: Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free

A handwritten signature in black ink, appearing to read 'Guy Degriek', written over a horizontal line.

Guy Degriek

Manager, Product Environmental Compliance

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中国电子电气产品中有害物质的名称及含量
China EEP Hazardous Substance Information



Restricted Materials Above Threshold

部件名称 (Component Name) 1393217-8	有害物质 Hazardous Substance					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
继电器 (Relays)	O	O	X	O	O	O

本表格依据SJ/T 11364标准的规定编制。

This table is compiled according to SJ/T 11364 standard.

- O: 表示该有害物质在该部件所有均质材料中的含量均在GB/T 26572标准规定的限量要求以下。
Indicates that the concentration of the hazardous substance in all homogeneous materials of the part is below the relevant threshold of the GB/T 26572 standard.
- X: 表示该有害物质至少在该部件的某一均质材料中的含量超出GB/T 26572标准规定的限量要求。
Indicates that the concentration of the hazardous substance in at least one homogeneous material of the part is above the relevant threshold of the GB/T 26572 standard.

电子电气产品的环保使用期限依据SJ/T 11388标准的规定确定。

The EPUP value of EEP is defined according to SJ/T 11388 standard.

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